International Rectifier

DirectFET Large Can

RoHS Compliance Document

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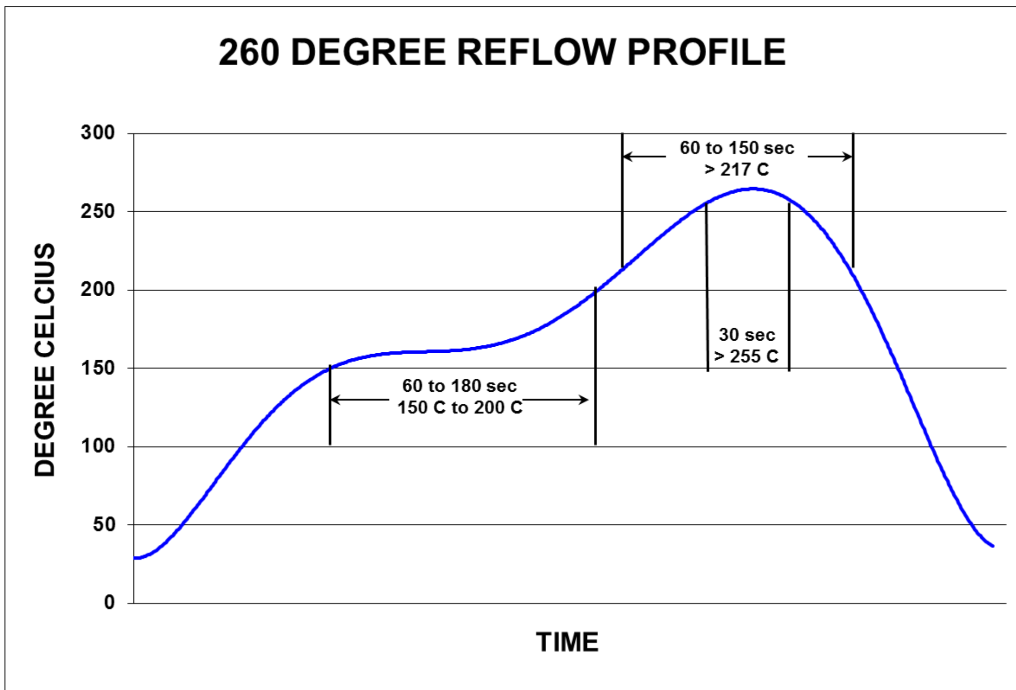
Dec. 2015

IOR International Rectifier

DirectFET - Large Can

Component	Material Name	Material Mass (g)	Element Name Composition	CAS #	Substance Mass (g)	Material Analysis Weight (%)	% of Total Weight
Chip	Silicon	0.01442	Si	7440-21-3	0.01374	95%	7.8%
			Epoxy	90598-46-2	0.00068	5%	0.4%
Lead Frame	Plated Copper	0.15674	Cu	7440-50-8	0.15343	97%	86.9%
			Ni	7440-02-0	0.00092	1%	0.5%
			Ag	7440-22-4	0.00239	2%	1.3%
Die Attach	Silver Epoxy	0.00374	Ag	7440-22-4	0.00280	75%	1.6%
			Epoxy	90598-46-2	0.00094	25%	0.5%
Solder	Solder Bumps	0.00162	Sn	7440-31-5	0.00151	93%	0.9%
			Ag	7440-22-4	0.00009	6%	0.1%
			Cu	7440-50-8	0.00002	1%	0.0%
			Total Weight (g)		**0.17652**		

No tin whisker mitigation strategy



This part is compliant with EU Directive 2011/65/EU (RoHS Directive) and does not contain lead, mercury, cadmium (0.01%), hexavalent chromium, PBB or PBDE in concentrations greater than 0.1%, except as permitted by Annex III. Further part complies with 3 reflow cycles per JEDEC J-STD-020

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